

Part Number: AAAF5051-03



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Blue
Reddish-Orange
Green

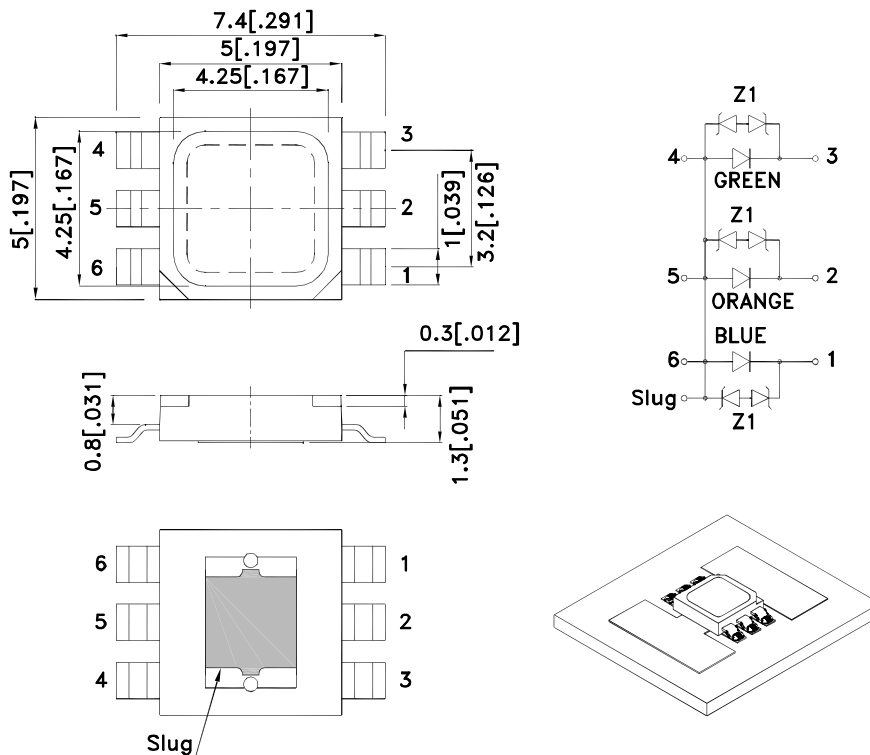
Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- White SMD package, silicone resin.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Blue source color devices are made with InGaN on Al₂O₃ substrate Light Emitting Diode.
This devices are made with AlGaInP.
The Green source color devices are made with InGaN on Al₂O₃ substrate Light Emitting Diode.
Static electricity and surge damage the LEDs.
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.15[\pm 0.006]$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

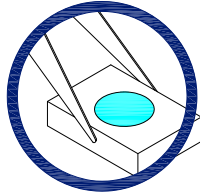


Handling Precautions

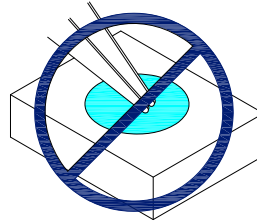
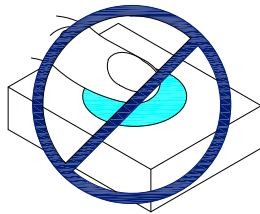
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

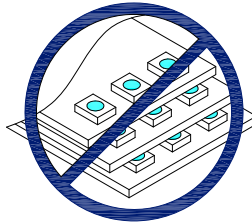
1. Handle the component along the side surfaces by using forceps or appropriate tools.



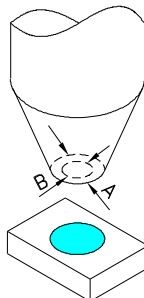
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 150mA*120mA		Φv (mlm) [2] @ 150mA*120mA		Viewing Angle [1]
			Min.	Typ.	Min.	Typ.	2θ1/2
AAAF5051-03	Blue (InGaN)	WATER CLEAR	650	1000	3500	4500	120°
	Reddish-Orange (AlGaInP)		*2500	*4000	*7200	*9000	
	Green (InGaN)		3800	6000	14000	20000	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%. *Luminous intensity with asterisk is measured at 120mA.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Device	Value	Unit	Test Conditions
Power dissipation	PD	Blue	0.6	W	If=150mA If=120mA If=150mA
		Reddish-Orange	0.336		
		Green	0.6		
Junction temperature	TJ	Blue	140	°C	If=150mA If=120mA If=150mA
		Reddish-Orange	140		
		Green	140		
Operating Temperature	Top	Blue	-40 To +85	°C	If=150mA If=120mA If=150mA
		Reddish-Orange			
		Green			
Storage Temperature	Tstg	Blue	-40 To +85	°C	If=150mA If=120mA If=150mA
		Reddish-Orange			
		Green			
DC Forward Current [1]	IF	Blue	150	mA	If=150mA If=120mA If=150mA
		Reddish-Orange	120		
		Green	150		
Peak Forward Current [2]	IFM	Blue	300	mA	If=150mA If=120mA If=150mA
		Reddish-Orange	300		
		Green	300		
Thermal resistance	Rth j-a	Blue	230	°C/W	If=150mA If=120mA If=150mA
		Reddish-Orange	300		
		Green	220		
Thermal resistance	Rth j-s	Blue	30	°C/W	If=150mA If=120mA If=150mA
		Reddish-Orange	50		
		Green	35		
Reverse Current	IR	Blue	10	uA	VR=5V
		Reddish-Orange	10		
		Green	10		

Notes:

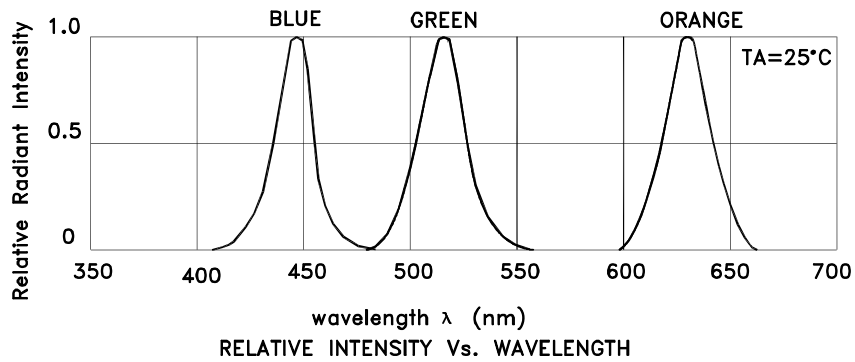
1. Results from mounting on Aluminum Board.
2. 1/10 Duty Cycle, 0.1ms Pulse Width.

Electrical / Optical Characteristics at Ta=25°C

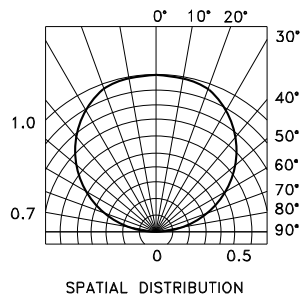
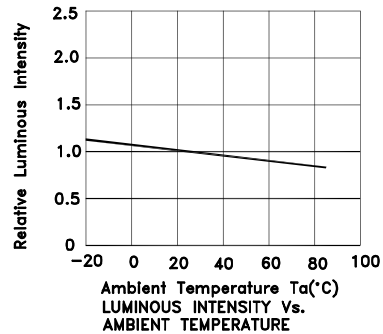
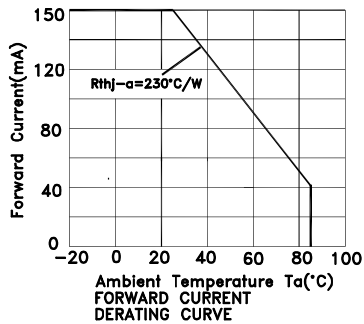
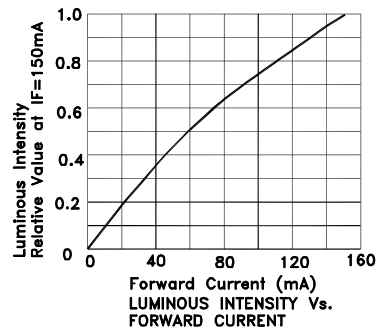
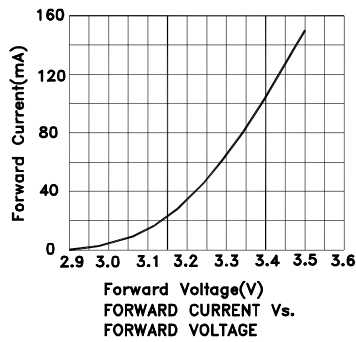
Parameter	Symbol	Device	Value			Unit
			Min.	Typ.	Max.	
Wavelength at peak emission If=150mA	λ peak	Blue		445		nm
Wavelength at peak emission If=120mA		Reddish-Orange		633		
Wavelength at peak emission If=150mA		Green		515		
Dominant Wavelength If=150mA	λ dom [1]	Blue		450		nm
Dominant Wavelength If=120mA		Reddish-Orange		624		
Dominant Wavelength If=150mA		Green		525		
Spectral Line Half-width If=150mA	$\Delta\lambda$ 1/2	Blue		20		nm
Spectral Line Half-width If=120mA		Reddish-Orange		30		
Spectral Line Half-width If=150mA		Green		30		
Forward Voltage If=150mA	VF [2]	Blue	3.0	3.5	4.0	V
Forward Voltage If=120mA		Reddish-Orange	2.0	2.3	2.8	
Forward Voltage If=150mA		Green	3.0	3.5	4.0	
Reverse Voltage	VR	Blue		5		V
		Reddish-Orange		5		
		Green		5		
Temperature coefficient of λ peak If=150mA, -10 ° C ≤ T ≤ 100 ° C	TC λ peak	Blue		0.12		nm/° C
Temperature coefficient of λ peak If=120mA, -10 ° C ≤ T ≤ 100 ° C		Reddish-Orange		0.09		
Temperature coefficient of λ peak If=150mA, -10 ° C ≤ T ≤ 100 ° C		Green		0.13		
Temperature coefficient of λ dom If=150mA, -10 ° C ≤ T ≤ 100 ° C	TC λ dom	Blue		0.1		nm/° C
Temperature coefficient of λ dom If=120mA, -10 ° C ≤ T ≤ 100 ° C		Reddish-Orange		0.03		
Temperature coefficient of λ dom If=150mA, -10 ° C ≤ T ≤ 100 ° C		Green		0.11		
Temperature coefficient of VF If=150mA, -10 ° C ≤ T ≤ 100 ° C	TCv	Blue		-2.3		mV/° C
Temperature coefficient of VF If=120mA, -10 ° C ≤ T ≤ 100 ° C		Reddish-Orange		-2.7		
Temperature coefficient of VF If=150mA, -10 ° C ≤ T ≤ 100 ° C		Green		-3.9		

Notes:

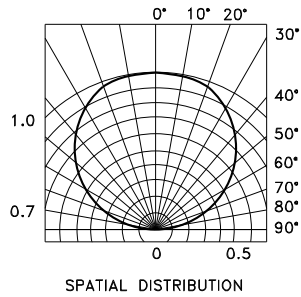
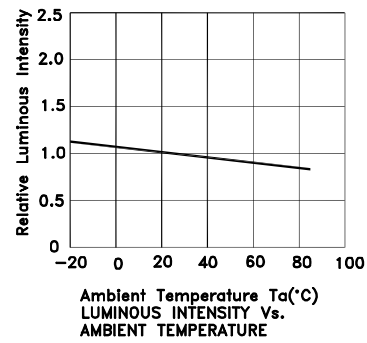
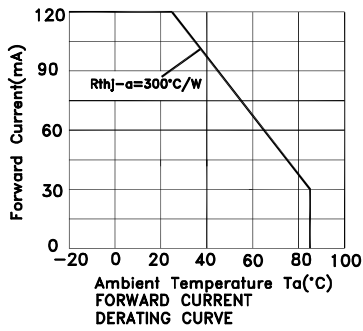
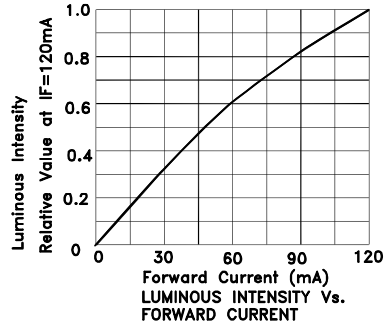
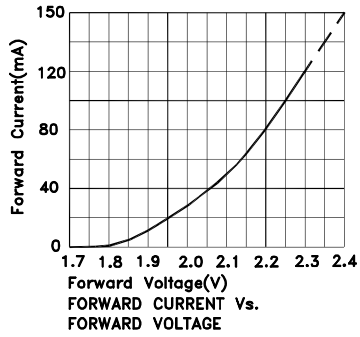
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.2V.



AAAF5051-03 Blue

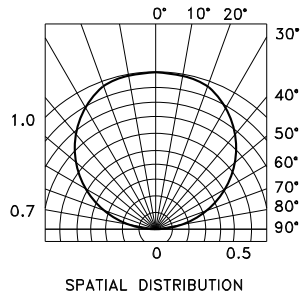
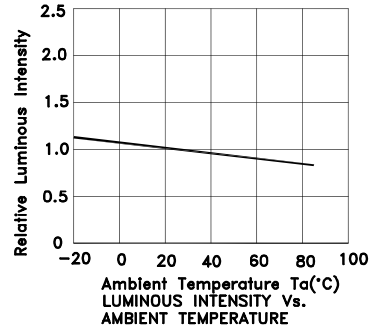
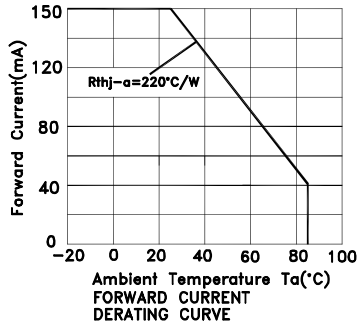
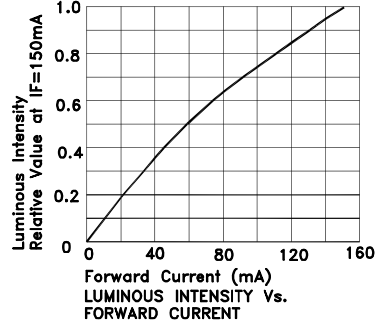
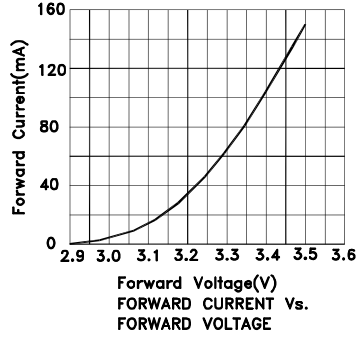


Reddish-orange



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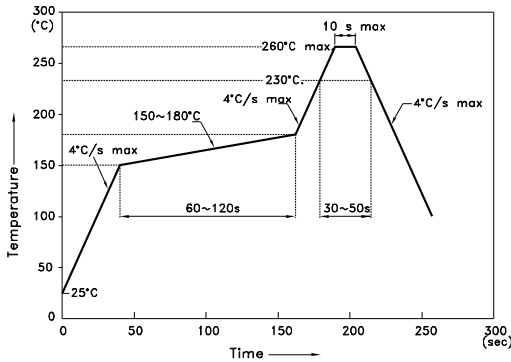
Green



AAAF5051-03

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

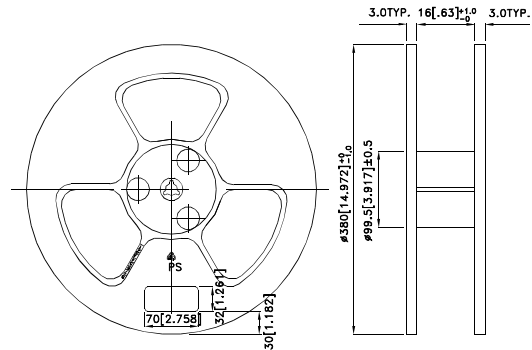
Reflow Soldering Profile For Lead-free SMT Process.



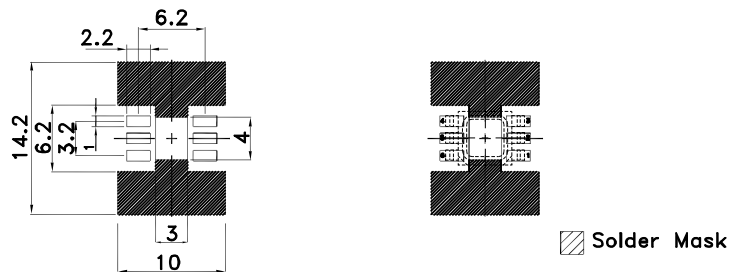
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

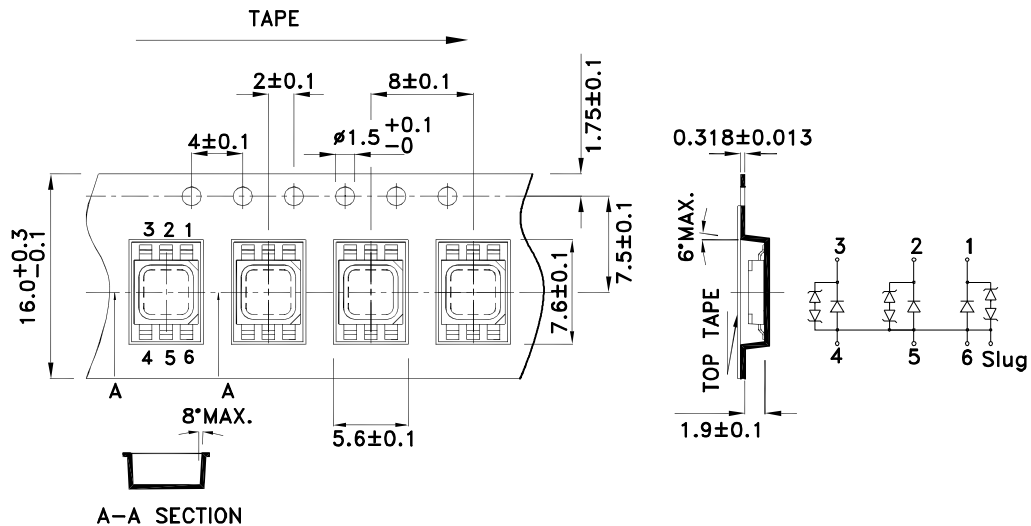
Reel Dimension



Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



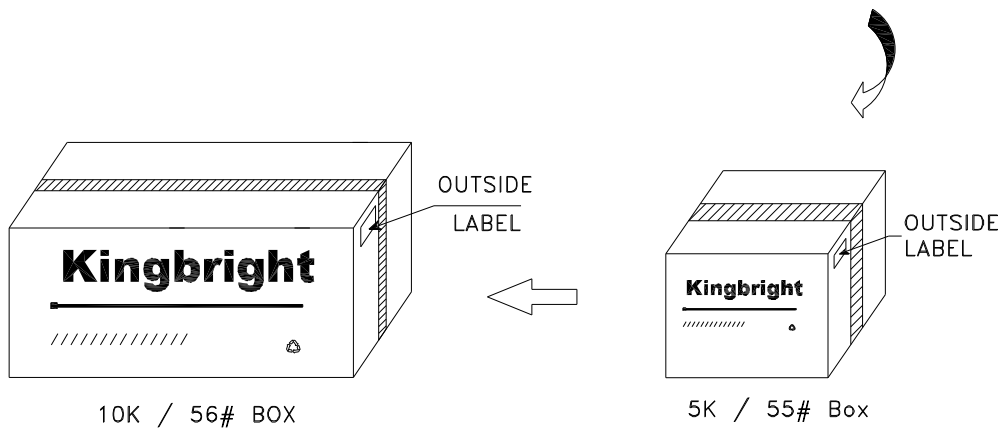
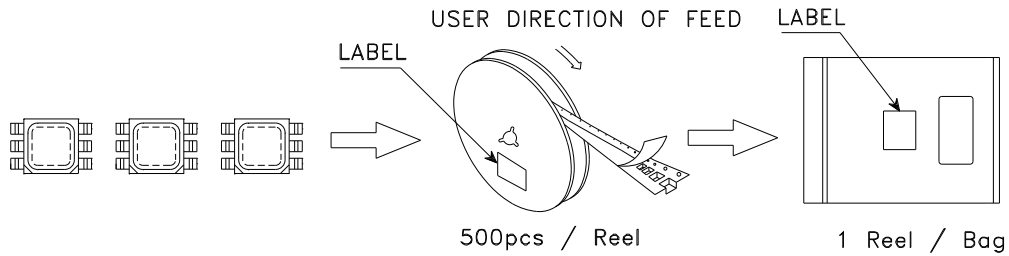
Tape Specifications (Units : mm)




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PACKING & LABEL SPECIFICATIONS

AAAF5051-03



<h1>Kingbright</h1>	
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QTY: 500 pcs	Q.C. Q C xx xx xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	